## RESPONSE UNDER 37 CFR 1.116 **EXPEDITED PROCEDURE EXAMINING GROUP 2811**

PATENT APPLICATION Docket No.: 9903-068 Client Ref. No.: S03US008

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Dae-Woo SON, et al.

Serial No.:

10/739,456

Examiner:

Owens, Douglas W.

Filed:

December 17, 2003

Group Art Unit:

2811

Confirmation No.:

9321

For:

TAPE CIRCUIT SUBSTRATE HAVING WAVY BEAM LEADS AND

SEMICONDUCTOR CHIP PACKAGE USING THE SAME

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## AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, Paper No. 20060310, dated March 16, 2006, please amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 9 of this paper.

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